



Virtex-4 and Virtex-5 QV FPGA CF Package Assembly Location Change

XCN13005 (v2.0) September 22, 2014

Product Change Notice

Overview

The purpose of this notification is to communicate that Xilinx is discontinuing the current Virtex[®]-4 and Virtex[®]-5 QV FPGA Ceramic Flip Chip Column Grid Array (CF package code) parts due to current supplier line discontinuance. However, Xilinx will continue to offer Virtex-4 and Virtex-5 QV FPGA Ceramic Flip Chip Column Grid Array products under a new CN package code with a new assembly supplier.

Description

Xilinx's supplier, IBM is shutting down their Ceramic Flip Chip assembly line including column attach of the Ceramic Column Grid Array (CCGA). The supplier line shutdown has impacted the Virtex-4 and Virtex-5 QV FPGA ceramic CF package products. To ensure supply continuity, Xilinx is in the process of qualifying new assembly and column attach suppliers with new part numbers released for production. The qualification is now targeted to complete by December, 2014.

Virtex-4 and Virtex-5 FPGA QV Ceramic Flip Chip packages are now offered in Column Grid Array products (with solder columns), and will be qualified with a new Bill of Material (underfill, lid and lid attach adhesive, eutectic bumps, and solder columns) at the new suppliers.

Products Affected

The products affected by this change are included in [Table 1](#).

Table 1: Products Affected

Part Number (CF)	Replacement Part (CN)
XCDAISY-CF1140	XCDAISY-CN1140
XCDAISY-CF1144	XCDAISY-CN1144
XCDAISY-CF1509	XCDAISY-CN1509
XQDAISY-CF1752	XQDAISY-CN1752
XQR4VFX140-10CF1509V	XQR4VFX140-10CN1509V
XQR4VFX60-10CF1144V	XQR4VFX60-10CN1144V
XQR4VLX200-10CF1509V	XQR4VLX200-10CN1509V
XQR4VSX55-10CF1140V	XQR4VSX55-10CN1140V
XQR5VFX130-1CF1752B	XQR5VFX130-1CN1752B
XQR5VFX130-1CF1752V	XQR5VFX130-1CN1752V

Traceability

Below examples are difference between the CF package and CN package parts (drawings not to scale):

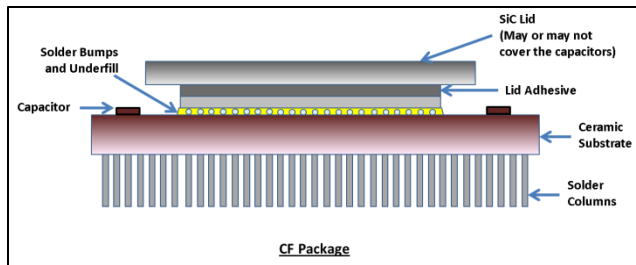


Figure 1: CF Package

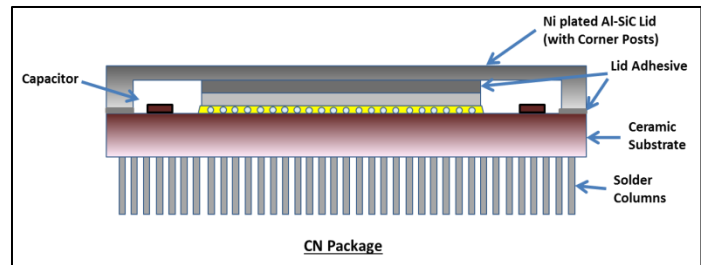


Figure 2: CN Package

Key Dates and Ordering Information

Xilinx had offered a last time buy opportunity for all IBM built products listed in [Table 1](#), which has closed.

For customers expecting to order devices assembled by the new suppliers, Xilinx is expecting to complete supplier and product qualification in December, 2014.

Order entry for XQR5VFX130-1CN1752B and XQR5VFX130-1CN1752V will start on October 1, 2014 with devices shipping after qualification has completed.

XQDAISY-CN1752 is now open for order, contact factory for lead time.

Order entry for all remaining devices shown in [Table 1](#) will be opened upon qualification completion.

All orders will be Non-Cancellable, Non-Returnable (NCNR).

For information associated with the development of the new supplier, please contact your local Xilinx Sales representative.

Qualification

Qualification data for the new replacement products shown in [Table 1](#) will be available upon request in CYQ1, 2015.

Response

No response is required. For additional information or questions, please contact [Xilinx Technical Support](#).

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Revision History

The following table shows the revision history for this document:

Date	Version	Description of Revisions
2/25/13	1.0	Initial release.
09/22/14	2.0	Migrating from Ceramic Flip chip "Land" grid to Flip chip "Column" grid array for Virtex-4 and Virtex-5 QV FPGA CF Package. Also, re-adjust the key dates and ordering information.

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